

江西省晶能半导体有限公司

JiangXi LatticePower Semiconductor Corporation

产 品 规 格 书

Specification

产品名称 **Product Name:** UXFO-Y3

产品型号 **Product P/N:** _____

客 户 **Client name:** _____

客户料号 **Client P/N:** _____

版 本 号 **Version No.:** V002

日 期 **Sending Date:** _____

客户承认栏 Client Approval	
核准 Approval	确认 Audit

制定 **Confirmation:** _____ 审核 **Approval:** _____

工厂地址:江西省南昌市高新区艾溪湖北路 699 号

Address: No.699 Aixihu North Road, Nanchang, Jiangxi Province, China

目录

Contents

1、特点 Features.....	1
2、应用 Applications.....	1
3、特征性能 Characteristic performance.....	2
4、产品代码 Product Order Code.....	3
5、分档规则 Bin Regulations.....	4
6、光电特性图 The Photoelectric Characteristics Graph.....	5
7、产品尺寸&产品电路 Product Size & Product Circuit.....	6
8、回流焊特性 Reflow Soldering Characteristics.....	8
9、卷轴 Reel Dimensions.....	9
10、可靠性验证 Reliability.....	10
11、注意事项 Cautions.....	12

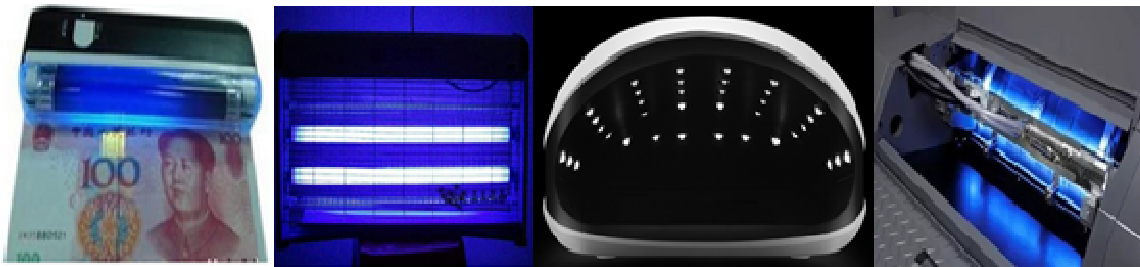
1、特点 Features



- ◆ Al₂O₃ 陶瓷封装
Al₂O₃ Ceramic Substrate package
- ◆ 尺寸：3.5mm*3.5mm
Size: 3.5mm*3.5mm
- ◆ 齐纳管保护
Zener Protection
- ◆ 适于 SMT 贴片
Compatible with SMT
- ◆ 发光角度：120°
Viewing Angle: 120°
- ◆ 包装：最大 1000 颗/卷
Package: Max: 1000pcs /reel

2、应用 Applications

宝石鉴定	Gem Identification
金属探伤	Metal defect detection
验钞	Money Detect



3、特征性能 Characteristic performance

a) 绝对最大额定值 Absolute Maximum Ratings

参数 Parameter	符号 Symbol	最大参数值 Maximum Rating	单位 Unit
电流 Forward Current (DC)	I _F	700	mA
功率 Power Dissipation	P	2.8	W
反向电压 Reverse Voltage	V _R	5	V
工作温度 Operating Temperature Range	T _{opr}	-40~80	°C
存储温度 Storage Temperature	T _{stg}	-40~105	°C
ESD (人体模式) ESD Human Body Mode	----	8000	V

b) 光电参数 Photoelectric parameters (T solder pad =25 °C, I_F =350mA)

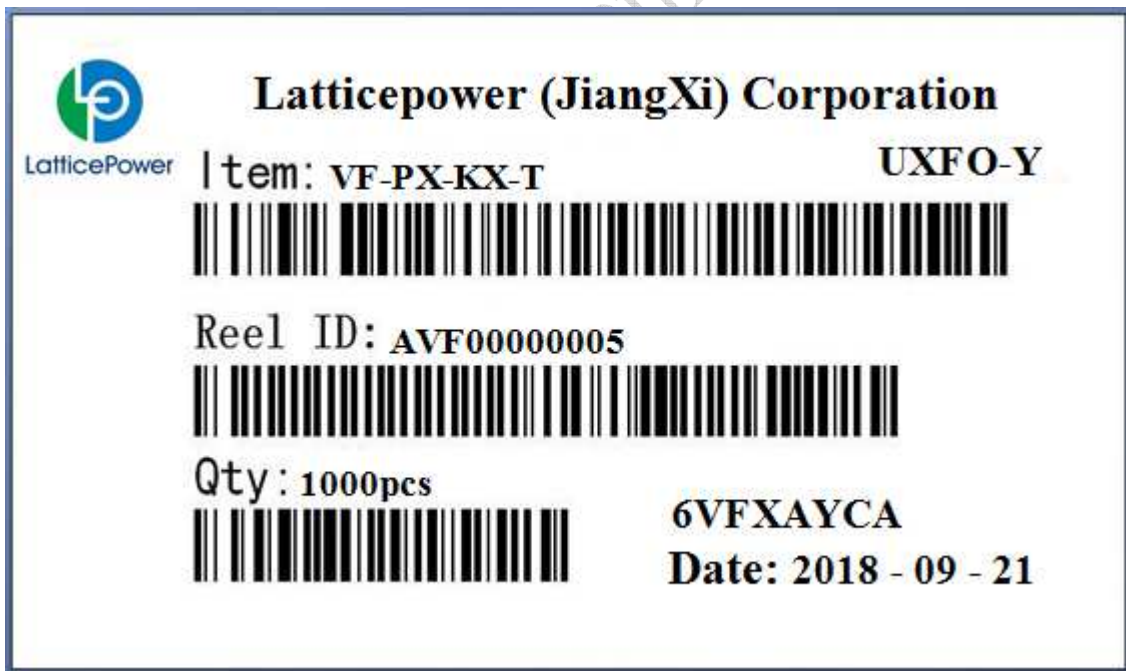
项目 Item	符号 Symbol	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
峰值波长 Peak Wavelength	WLP	367.5	----	372.5	nm
辐射功率 Radiation Power	Φ _e	200	430	----	mW
正向电压 Forward Voltage	V _F	3.4	----	4.0	V
发光角度 Viewing Angle	2θ _{1/2}	----	120	----	°
热阻 Thermal Resistance	----	----	6.7	----	°C/W
结温 LED Junction Temperature	T _j	----	90	----	°C

4、产品代码 Product Order Code

VF - PX - KX - T
① ② ③ ④

- ① 产品型号 Product Type
- ② 峰值波长等级 Peak Wavelength level
- ③ 辐射功率等级 Radiation Power level
- ④ 电压等级 VF Level

出货标签(例) Shipping label (e.g.)



5、分档规则 Bin Regulations

a) 峰值波长分档 Peak Wavelength Groups (T solder pad = 25°C, I_F = 350 mA)

代码 Group Code	最小值 Min.	最大值 Max.
PW	367.5	370
PX	370	372.5
PY	372.5	375

备注 Notes :

◇ 峰值波长测试误差±1.5nm。

It maintains a tolerance of ±1.5nm on peak wavelength measurements.

b) 辐射功率分档 Radiation Power Groups (T solder pad = 25°C, I_F = 350 mA)

代码 Group Code	最小值 Min.	最大值 Max.
KW	200	300
KX	300	800

备注 Notes :

◇ 辐射功率测试误差±8%。

It maintains a tolerance of ±8% on Radiation Power measurements.

c) 电压分档 Voltage Groups (T solder pad = 25°C, I_F = 350 mA)

代码 Group Code	最小值 Min.	最大值 Max.
T	2.9	3.9
T1	3.9	4.2

备注 Notes :

◇ 电压测试误差±0.1V。

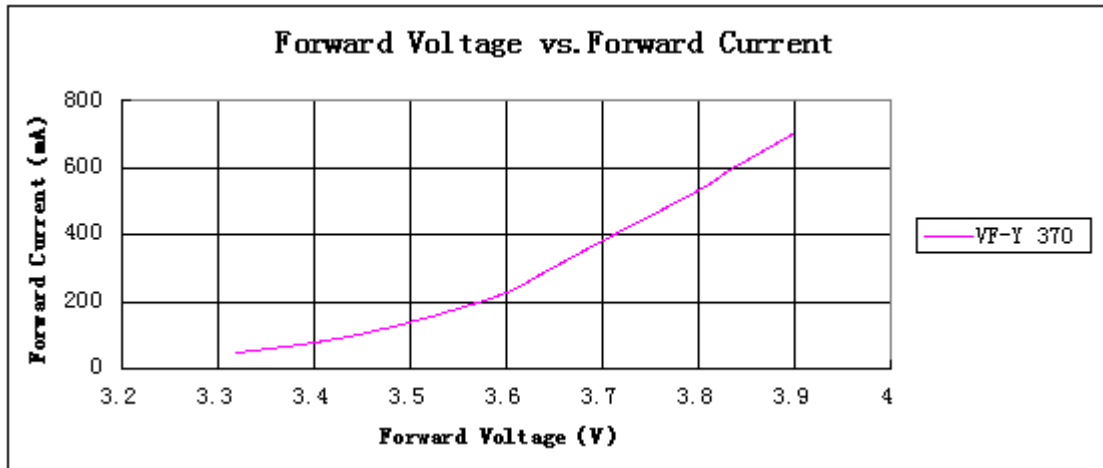
It maintains a tolerance of ±0.1V on Voltage measurements.

6、光电特性图

The Photoelectric Characteristics Graph (Ta=25 °C)

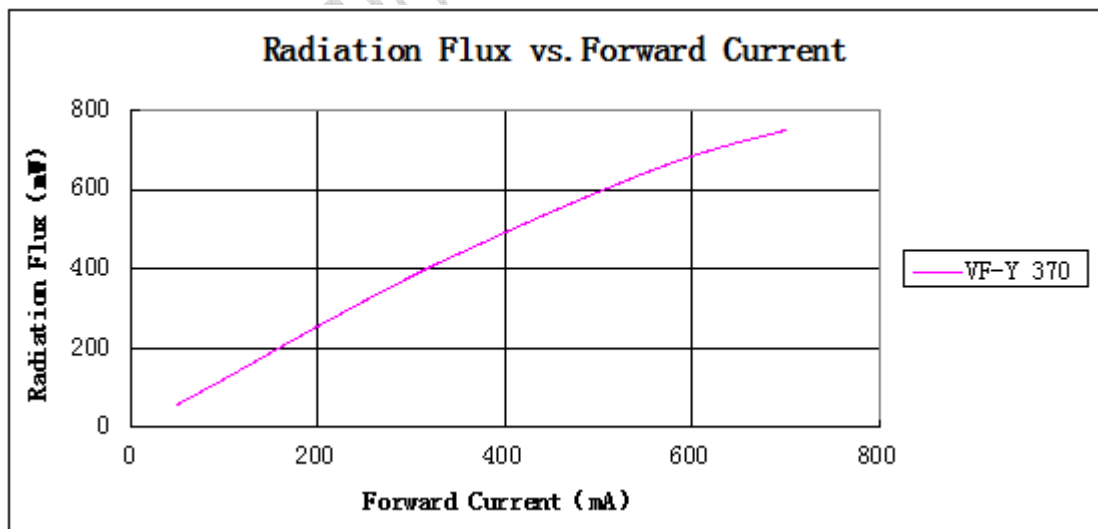
a) 正向电流-正向电压曲线

Forward Voltage VS. Forward Current Curve



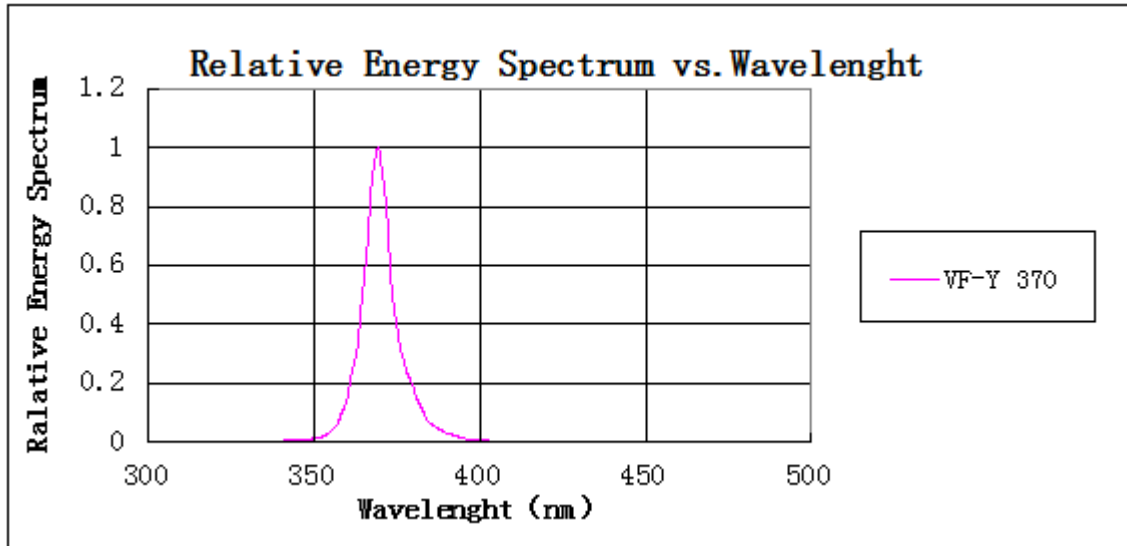
b) 辐射功率-正向电流曲线

Radiation Flux VS. Forward Current Curve



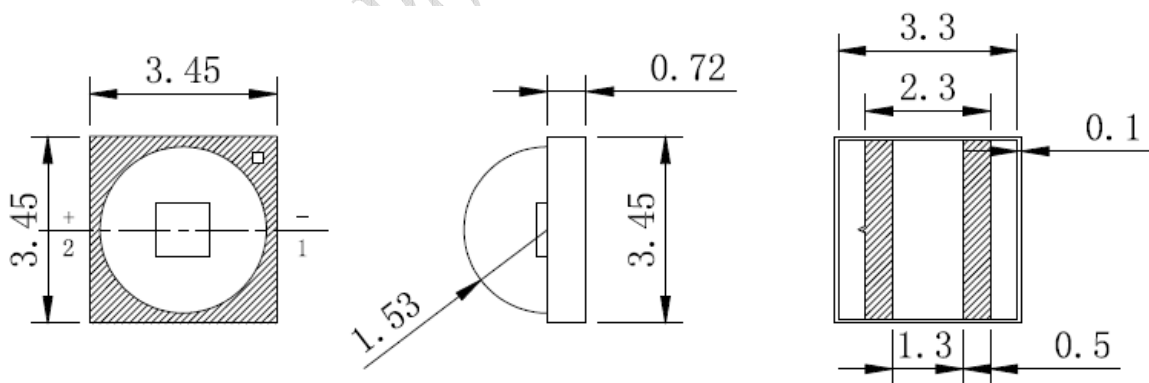
c) 相对能量-波长光谱曲线

Relative Energy Spectrum VS. Wavelength

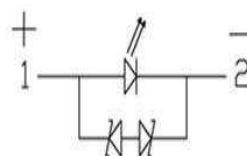


7、产品尺寸&产品电路 Product Size & Product Circuit

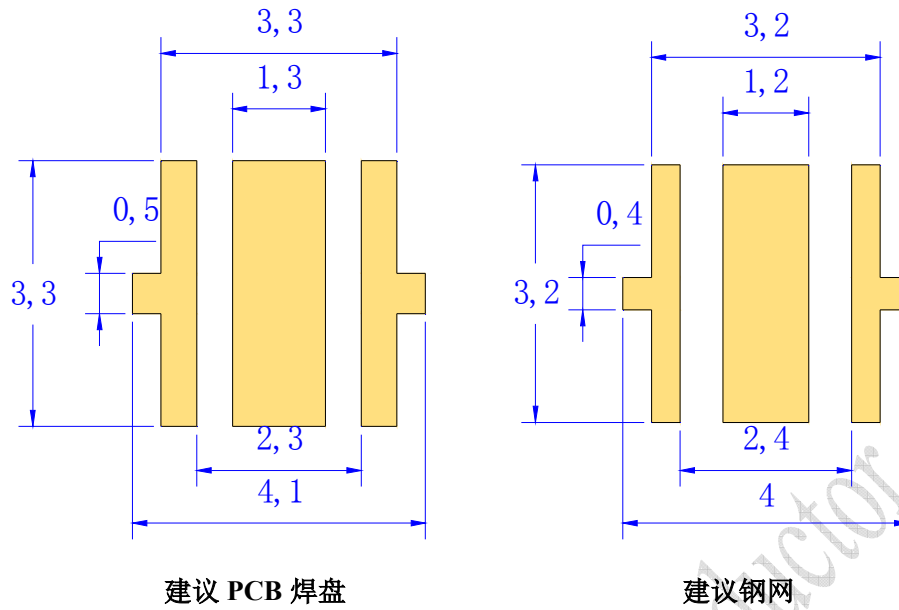
产品尺寸 Product Dimensions:



产品电路 Product Circuit:



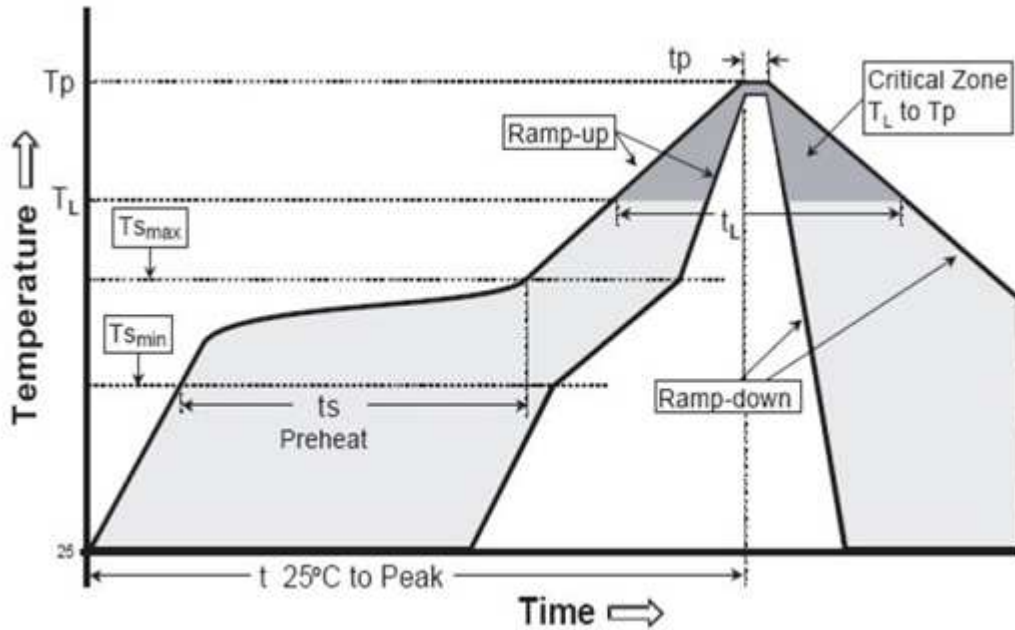
PCB 焊盘尺寸 PCB Pad Dimensions:



备注 Notes:

- ◇ 所有尺寸均以 mm 为单位
All dimensions are in millimeters
- ◇ 尺寸未按照公差 $\pm 0.1\text{mm}$ 标记的, 按照图纸标记
Size is not marked in accordance with tolerance $\pm 0.1\text{mm}$ and dimension tolerances in accordance with drawings

8、回流焊特性 Reflow Soldering Characteristics

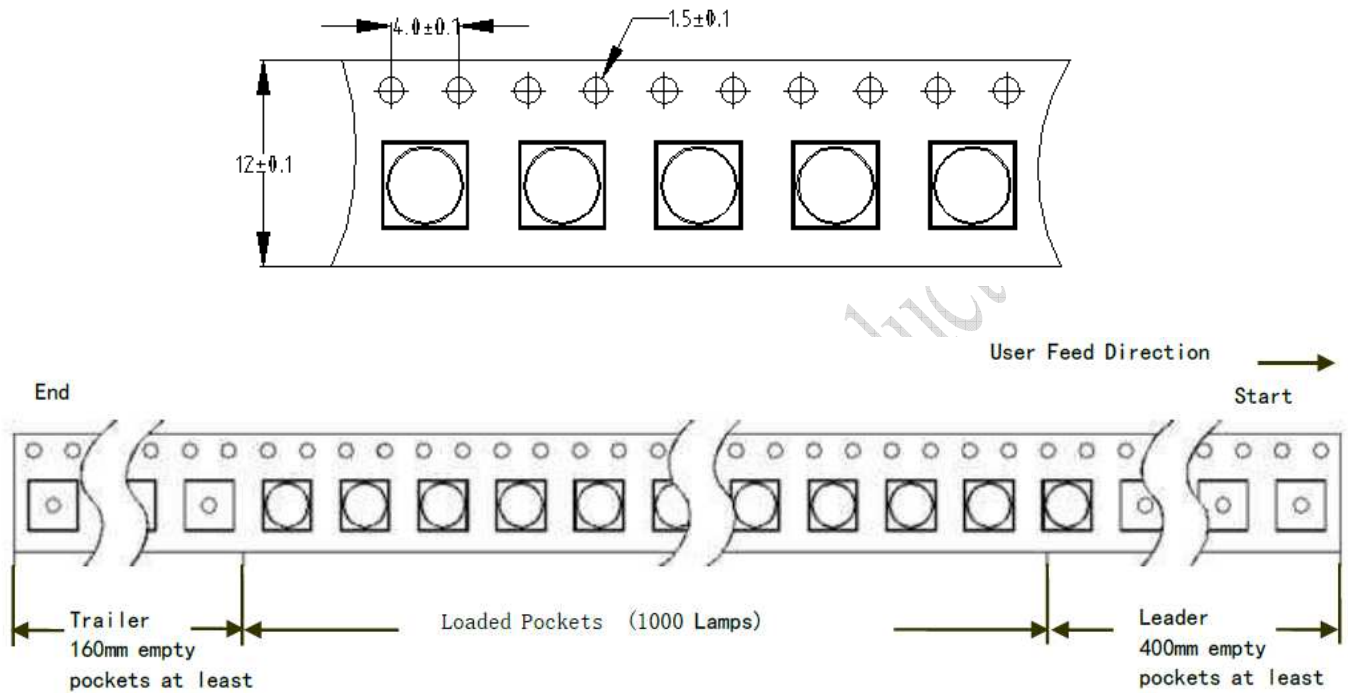


根据 EDEC-J-STD-020D 内容，参考以下内容。

Compatible with the JEDEC-J-STD-020D, using the parameters listed below.

特制参数 Profile Feature	无铅焊料 Lead-Free Solder	铅基焊料 Lead-Based Solder
平均上升速率 (T _{Smax} 至 T _p) Average Ramp-Up Rate (T _{Smax} to T _p)	3 °C/sec max.	3 °C/sec max.
预热: 温度最小值 (T _{Smin}) Preheat: Temperature Min (T _{Smin})	150°C	100°C
预热: 最高温度 (T _{Smax}) Preheat: Temperature Max (T _{Smax})	200°C	150°C
预热: 时间 (t _{Smin} 到 t _{Smax}) Preheat: Time (t _{Smin} to t _{Smax})	60-180 secs	60-120 secs
回流温度 (T _L) Time Maintained Above: Temperature (T _L)	217°C	183°C
回流时间 (t _L) Time Maintained Above: Time (t _L)	60-150 secs	60-150 secs
峰值/分类温度 (T _p) Peak/Classification Temperature(T _p)	255 ± 5°C	215 ± 5°C
实际峰值温度 (t _p) 在 5°C 以内的时间 Time Within 5°C of Actual Peak Temperature (t _p)	20-40 secs	10-30 secs
降低速率 Ramp-Down Rate	5°C/sec max.	5°C/sec max.

9、 卷轴 Reel Dimensions



备注 Notes:

- ◇ 卷轴包装 1000pcs
Reel:1000pcs.
- ◇ 卷轴包装方法符合 IJSC0806 (连续胶带上的电子元件包装)
The tape packing method complies with IJSC0806(Packing of Electronic Components on Continuous Tapes).
- ◇ 当卷轴由于工作中断而重绕时, 载带上压力不应超过 10N, 否则 LED 可能会粘在盖带上
When the tape is rewound due to work interruptions, no more than 10N should be applied to the embossed carrier tape.
The LEDs may stick to the cover tape.

10、可靠性 Reliability

a) 测试和结果 Tests and Results

测试项目 Test Item	参考标准 Reference Standard	测试条件 Test Conditions	测试周期 Test Duration	失效标准 Failure Criteria#	失效数/测试数 Units Failed/Tested
可焊性 (回流焊) Solderability(Reflow Soldering)	JEITA ED=4701 303 303A	$T_{\text{slid}}=255\pm 5^{\circ}\text{C}$, 5sec, Lead-free Solder(Sn-3.0Ag-0.5Cu)	3times	#2	0/22
高低温循环 Temperature Cycle	JEITA ED=4701 100 105	-40°C (30min)~ 25°C (5min)~ 85°C (30min)~ 25°C (5min)	100cycles	#1	0/22
高温/低温储存 High/Low Temperature Storage	JEITA ED=4701 200 201/ JEITA ED=4701 200 202	$T_A=120^{\circ}\text{C}/T_A=-40^{\circ}\text{C}$	1000h	#1	0/22
常温老化 Room Temperature Operating		$T_A=25^{\circ}\text{C}$, $I_F=700\text{mA}$ Test board: See NOTES below	1000h	#1	0/22
高温老化 High Temperature Operating		$T_A=55^{\circ}\text{C}$, $I_F=700\text{mA}$ Test board: See NOTES below	1000h	#1	0/22
高温高湿老化 Temperature Humidity Operating		85°C , RH=85%, $I_F=700\text{mA}$ Test board: See NOTES below	1000h	#1	0/22

b) 失效判定 Failure Criteria

判定 Criteria #	项目 Items	条件 Conditions	失效判定 Failure Criteria
#1	正向电压 Forward Voltage (V_F)	I_F	> 初始值×1.1 倍 > Initial value×1.1
	辐射功率 Radiation Power (Φ_e)	I_F	< 初始值×0.7 倍 < Initial value×0.7
	反向电流 Reverse Current (I_R)	$V_R=5V$	> 5uA > 5uA
#2	回流焊 Solderability	-	焊接面积<80% Less than 80% solder coverage

11、注意事项 Cautions

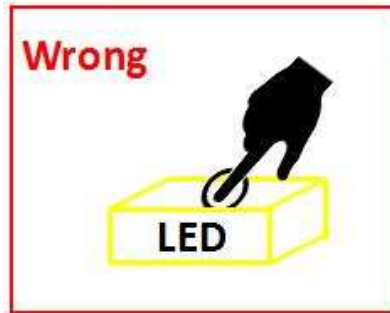
a) 存储 Storage

- 不要将芯片放在潮湿的地方，存放温度在 5°C~30°C 之间，相对湿度在 30% 以下。
Do not place the chips in damp places, Storage temperature between 5 °C and 30 °C, Relative humidity under 30%.
- 开包后建议在 24 小时内过完回流焊，车间条件 ≤30°C/60%RH。
After opening the package, it is recommended to finish the reflow within 24 hours. The workshop conditions are ≤30°C/60%RH
- 如果受潮，需将贴片卷盘放入 60°C 烤箱烘烤 24 小时；打开后，LED 灯可重新密封在原始真空袋中。
If it is wet, the patch reel should be baked in a 60 ° C oven for 24 hours; after opening, the LED light can be resealed in the original vacuum bag.
- 不要接触任何未知的液体，特别是丙酮。
Don't touch any unknown liquid, In particular, acetone.
- 防止静电死亡，手动操作需要戴橡胶手套并佩戴静电环。
Prevent electrostatic killed, Manual operation is required to wear rubber gloves and wear electrostatic ring.

b) 清洗 Cleaning

- 通常，LED 不建议对部件进行湿式清洁处理，因为封装不是密封的。
In general, LED does not recommend a wet cleaning process for component as the package is not hermetically sealed.
- 由于采用开放式设计，所有类型的清洁液都可能渗透到封装中，导致 LED 退化或完全失效。
Due to the open design, all kind of cleaning liquids can infiltrate the package and cause a degradation or a complete failure of the LED.

c) 操作注意 Handling Precautions



- 在处理过程中，还应注意确保组件顶面没有压力
During the handling, care should be taken as well to ensure no pressure on the top surface of component.
- 应避免使用所有类型的尖锐物体（例如镊子，指甲等），以防止对硅树脂造成压力，因为这会导致部件损坏。
All types of sharp objects(e.g. forceps, fingernail, etc) should be avoided in order to prevent stress to the silicone, since this can lead to damage of the component.

LatticePower Semiconductor